

**Description**

The SX5N10SI uses advanced trench technology to provide excellent  $R_{DS(ON)}$ , low gate charge and operation with gate voltages as low as 4.5V. This device is suitable for use as a Battery protection or in other Switching application.

**General Features**

$V_{DS} = 100V$   $I_D = 5A$

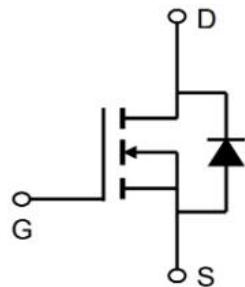
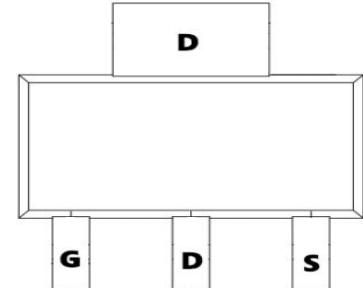
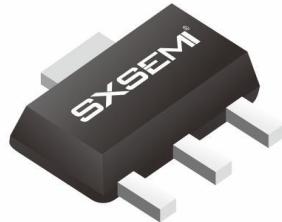
$R_{DS(ON)} < 110m\Omega$  @  $V_{GS}=10V$

**Application**

Lithium battery protection

Wireless impact

Mobile phone fast charging

**SOT-89-3L****Absolute Maximum Ratings ( $T_c=25^\circ C$  unless otherwise noted)**

Symbol	Parameter	Rating	Units
$V_{DS}$	Drain-Source Voltage	100	V
$V_{GS}$	Gate-Source Voltage	$\pm 20$	V
$I_D @ T_A=25^\circ C$	Continuous Drain Current, $V_{GS} @ 10V^1$	5	A
$I_D @ T_A=70^\circ C$	Continuous Drain Current, $V_{GS} @ 10V^1$	3.6	A
$I_{DM}$	Pulsed Drain Current <sup>2</sup>	15	A
$P_D @ T_A=25^\circ C$	Total Power Dissipation <sup>3</sup>	3.5	W
$T_{STG}$	Storage Temperature Range	-55 to 150	°C
$T_J$	Operating Junction Temperature Range	-55 to 150	°C
$R_{\theta JA}$	Thermal Resistance Junction-ambient <sup>1</sup>	85	°C/W
$R_{\theta JC}$	Thermal Resistance Junction-Case <sup>1</sup>	40	°C/W

**Electrical Characteristics ( $T_c=25^\circ\text{C}$  unless otherwise noted)**

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
BVDSS	Drain-Source Breakdown Voltage	$V_{GS}=0\text{V}$ , $I_D=250\mu\text{A}$	100	---	---	V
$\Delta BVDSS/\Delta TJ$	BVDSS Temperature Coefficient	Reference to $25^\circ\text{C}$ , $I_D=1\text{mA}$	---	0.122	---	$\text{V}/^\circ\text{C}$
RDS(ON)	Static Drain-Source On-Resistance <sup>2</sup>	$V_{GS}=10\text{V}$ , $I_D=3\text{A}$	---	88	110	$\text{m}\Omega$
		$V_{GS}=4.5\text{V}$ , $I_D=2\text{A}$	---	95	125	$\text{m}\Omega$
VGS(th)	Gate Threshold Voltage	$V_{GS}=V_{DS}$ , $I_D=250\mu\text{A}$	1.2	1.6	2.5	V
$\Delta V_{GS(\text{th})}$	$V_{GS(\text{th})}$ Temperature Coefficient		---	-4.84	---	$\text{mV}/^\circ\text{C}$
IDSS	Drain-Source Leakage Current	$V_{DS}=100\text{V}$ , $V_{GS}=0\text{V}$ , $T_J=25^\circ\text{C}$	---	---	10	$\text{uA}$
		$V_{DS}=100\text{V}$ , $V_{GS}=0\text{V}$ , $T_J=55^\circ\text{C}$	---	---	100	
IGSS	Gate-Source Leakage Current	$V_{GS}=\pm 20\text{V}$ , $V_{DS}=0\text{V}$	---	---	$\pm 100$	nA
gfs	Forward Transconductance	$V_{DS}=5\text{V}$ , $I_D=2\text{A}$	---	10.2	---	S
R <sub>g</sub>	Gate Resistance	$V_{DS}=0\text{V}$ , $V_{GS}=0\text{V}$ , $f=1\text{MHz}$	---	2.3	4.6	$\Omega$
Q <sub>g</sub>	Total Gate Charge (10V)	$V_{DS}=60\text{V}$ , $V_{GS}=10\text{V}$ , $I_D=2\text{A}$	---	25.5	---	nC
Qgs	Gate-Source Charge		---	4.2	---	
Qgd	Gate-Drain Charge		---	4.3	---	
Td(on)	Turn-On Delay Time	$V_{DD}=50\text{V}$ , $V_{GS}=10\text{V}$ , $R_G=3.3\Omega$ $I_D=1\text{A}$	---	17.3	---	ns
T <sub>r</sub>	Rise Time		---	2.8	---	
Td(off)	Turn-Off Delay Time		---	50	---	
T <sub>f</sub>	Fall Time		---	2.8	---	
Ciss	Input Capacitance	$V_{DS}=15\text{V}$ , $V_{GS}=0\text{V}$ , $f=1\text{MHz}$	---	677	---	pF
Coss	Output Capacitance		---	46	---	
Crss	Reverse Transfer Capacitance		---	32	---	
IS	Continuous Source Current <sup>1,4</sup>	$V_G=V_D=0\text{V}$ , Force Current	---	---	2	A
ISM	Pulsed Source Current <sup>2,4</sup>		---	---	4	A
VSD	Diode Forward Voltage <sup>2</sup>	$V_{GS}=0\text{V}$ , $I_S=1\text{A}$ , $T_J=25^\circ\text{C}$	---	---	1.2	V

**Note :**

- 1、The data tested by surface mounted on a 1 inch <sup>2</sup> FR-4 board with 2OZ copper.
- 2、The data tested by pulsed, pulse width  $\leq 300\mu\text{s}$ , duty cycle  $\leq 2\%$
- 3、The power dissipation is limited by  $150^\circ\text{C}$  junction temperature
- 4、The data is theoretically the same as  $I_{D(\text{on})}$  and  $I_{DM}$ , in real applications, should be limited by total power dissipation.

## Typical Characteristics

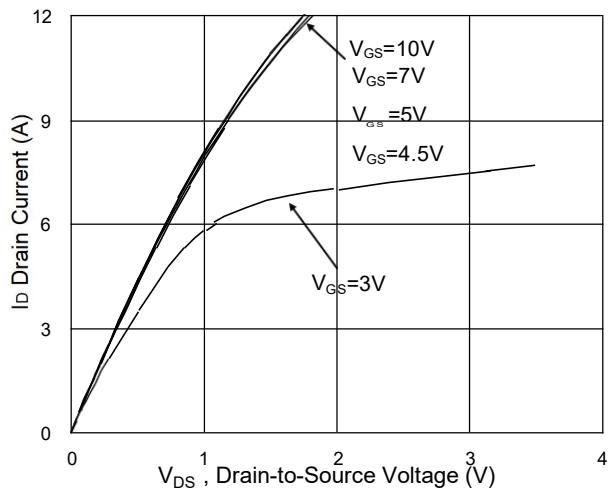


Fig.1 Typical Output Characteristics

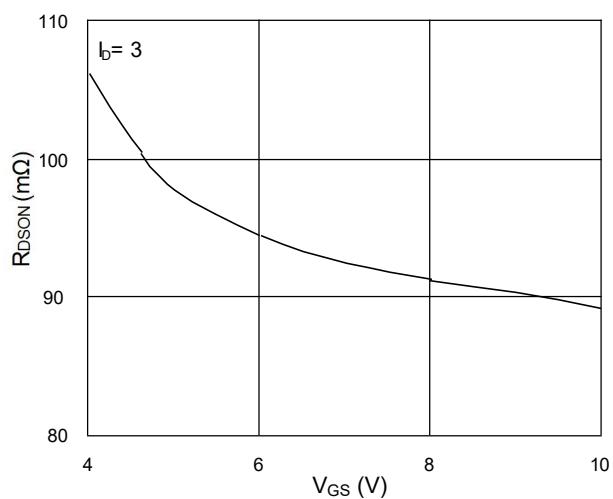


Fig.2 On-Resistance vs. Gate-Source

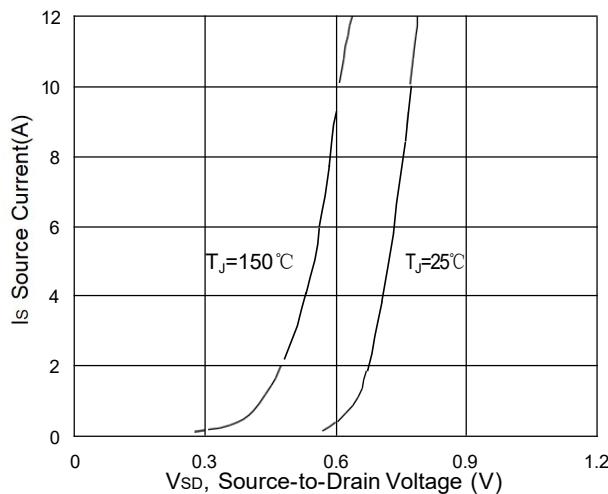


Fig.3 Forward Characteristics Of Reverse

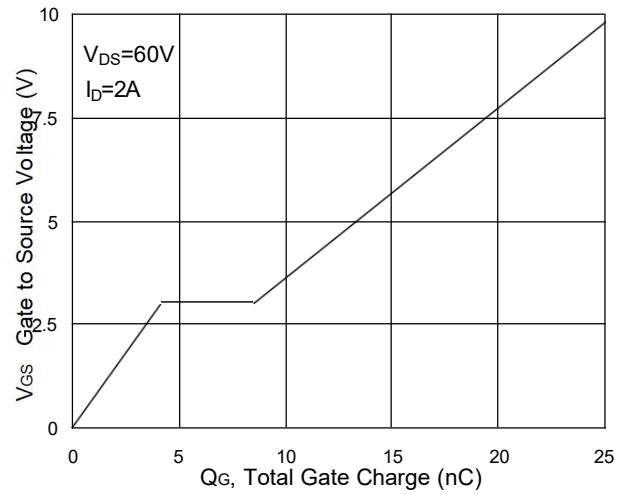


Fig.4 Gate-Charge Characteristics

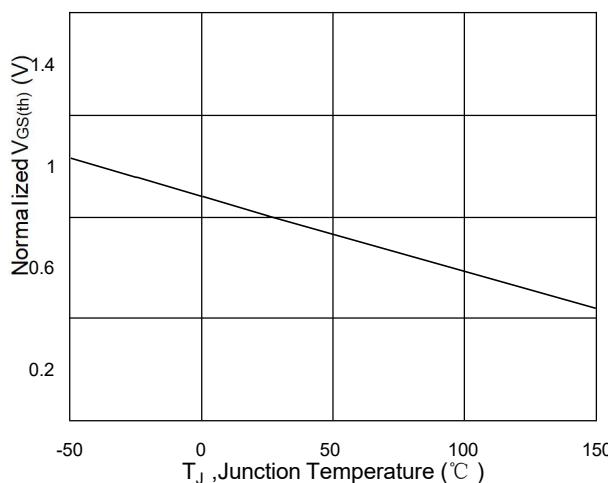


Fig.5 Normalized  $V_{GS(th)}$  vs.  $T_J$

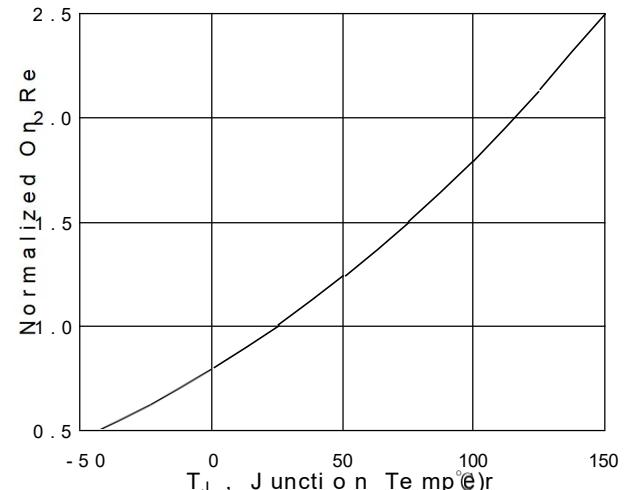


Fig.6 Normalized  $R_{DS(on)}$  vs.  $T_J$

### Typical Characteristics

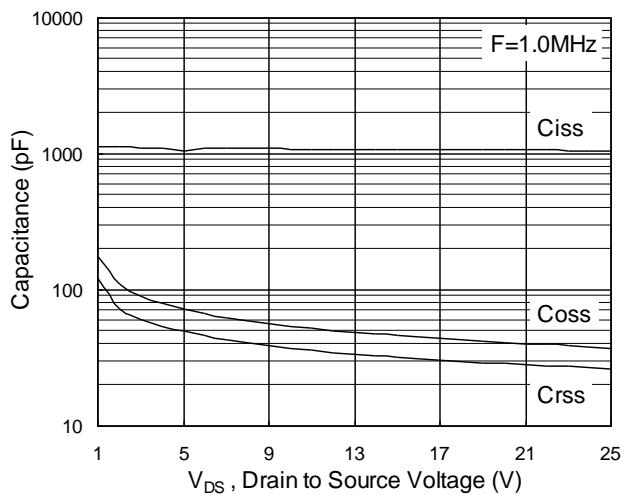


Fig.7 Capacitance

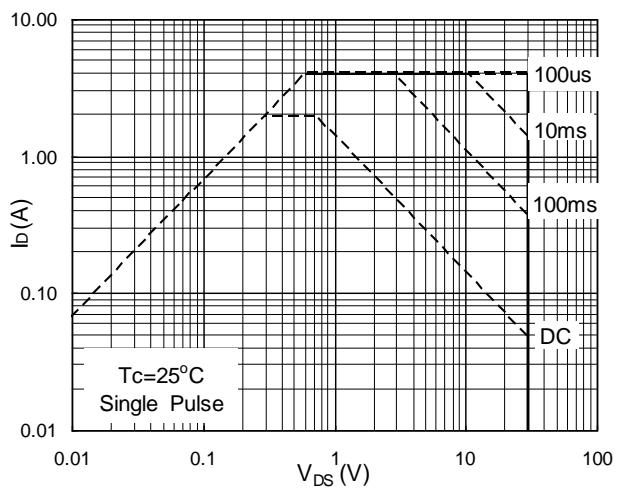


Fig.8 Safe Operating Area

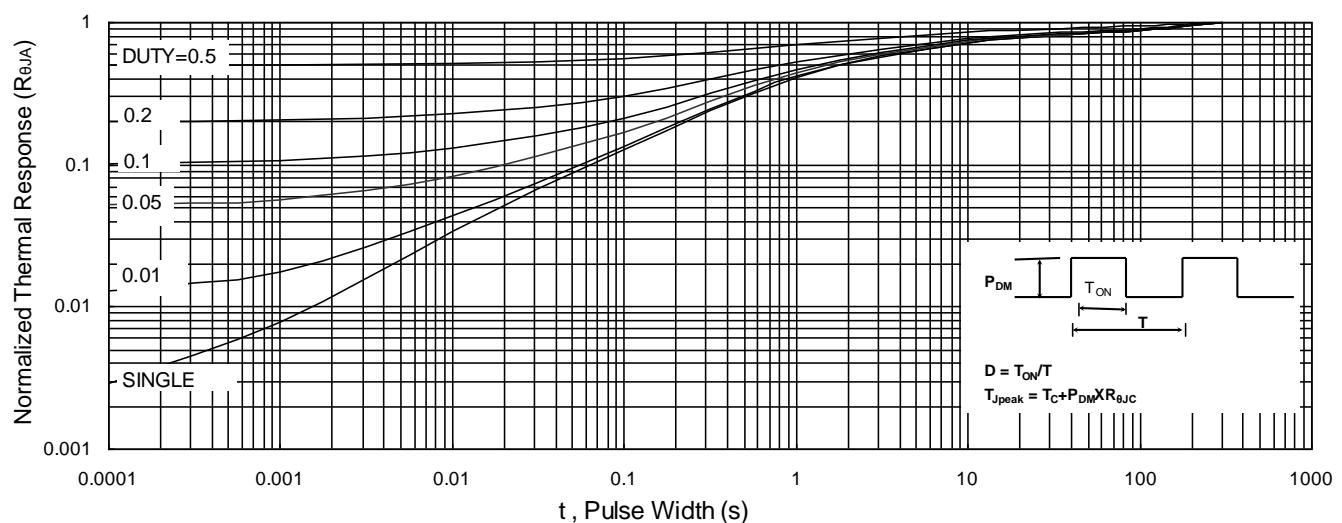


Fig.9 Normalized Maximum Transient Thermal Impedance

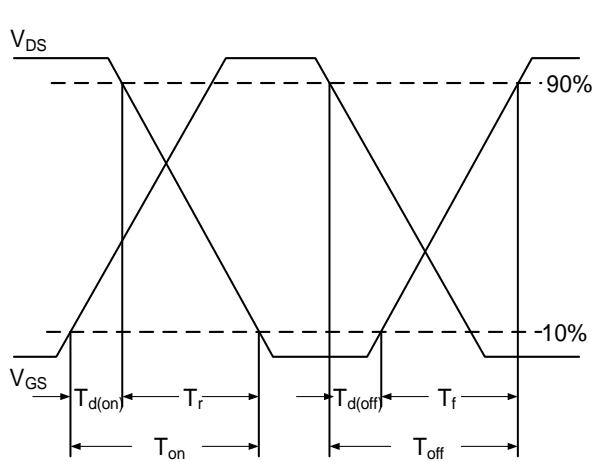


Fig.10 Switching Time Waveform

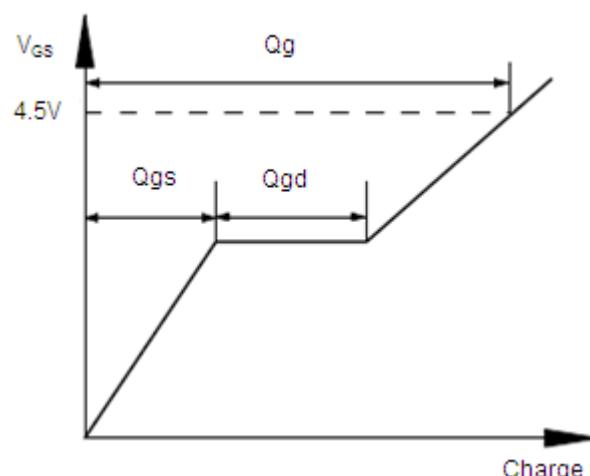
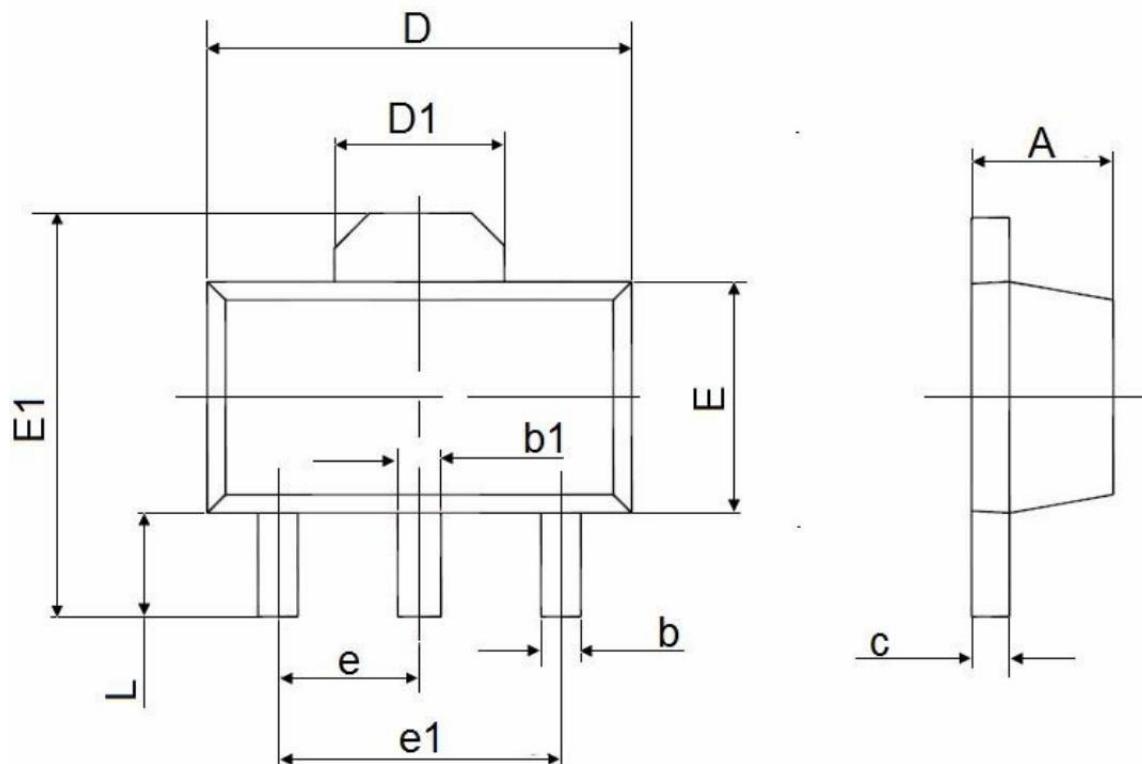


Fig.11 Gate Charge Waveform

**Package Mechanical Data-SOT89-3L-YX**

Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A	1.400	1.600	0.055	0.063
b	0.320	0.520	0.013	0.020
b1	0.400	0.580	0.016	0.023
c	0.350	0.440	0.014	0.017
D	4.400	4.600	0.173	0.181
D1	1.550 REF.		0.061 REF.	
E	2.300	2.600	0.091	0.102
E1	3.940	4.250	0.155	0.167
e	1.500 TYP.		0.060 TYP.	
e1	3.000 TYP.		0.118 TYP.	
L	0.900	1.200	0.035	0.047

**Package Marking and Ordering Information**

Product ID	Pack	Marking	Qty(PCS)
TAPING	SOT89-3L		3000